TEL: 886-7-6962211~3 http://www.sanho.com.tw FAX: 886-7-6976993 (Sales) E-mail: sanho@sanho.com.tw FAX: 886-7-6961782 (Export) E-mail: sanho@so-net.net.tw

FUJICURE FXR-1081

NO:TD-06-10

Fujicure FXR-1081 is not only a latent curing agent but also a curing accelerator.

FXR-1081 has the active hydrogen in molecule as well as the function group which act as a curing catalyst.

FXR-1081 is dispersed easily in epoxide resin resin and the resin mixture maintains good storage stability at room temperature.

Compared with the other Fujicure latent curing agents Fujicure FXE-1081 provides superior strength property at a lower curing temperature.

Additionally, even a small phr of FXR-1081 decreases the curing temperature to a great extent without deteriorating the original storage stability of the epoxy resin mixture when FXR-1081 is formulated in other latent curing agent.

The cured product using FXR-1081 is slightly yellowish but transparent and performs superior mechanical properties along with superior adhesion properties.

Encapsulation, potting, adhesive are recommendable application fields.

1. Typical specification:

(Not the fixed specification)

Appearance While powder / particle.

Specific gravity 1.11

Particle size 4µm on average.

Softening point 121° C

2. Property of the compounding

Epoxy resin ⁽¹⁾ , Phr	100	100	100	100	100
Aerosil 300 ⁽²⁾	1	1	1	1	1
FXR-1081	10	15	20	25	30
Gel time (3) (sec)					
at 70°C	1,404	953	734	573	459
at 80°C	753	534	437	362	333
at 100°C	353	251	197	169	161
at 120°℃	277	182	146	125	110
Storage stability (4)					
Viscosity increase ratio (in multiple)					
Initial viscosity, (Pa⋅S / 25°C)	23.7	27.5	32.3	38.8	46.3
40° C × 30 days	1.5	1.7	25days	16days	10dasy
23° C × 30 days	1.1	1.1	1.1	1.1	1.1
Gel time $^{(3)}(40^{\circ}\text{C} \times 30\text{days})$ (sec)					
at 70°C	1,171	812		_	_



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at 80°C	654	400	_	_	_
Gel time $^{(3)}(23^{\circ}\text{C} \times 30\text{days})$ (sec)					
at 70°C	1,387	942	703	508	439
at 80°C	743	526	423	357	302

Remarks:

- (1) Bisphenol-A liquid epoxy resin whose epoxy equivalent weight is about 190.
- (2) Colloidal silica by Nippon Aerosil.
- (3) Mess=2g, Measured by Yasuda model gel-timer.
- (4) Measure the storage stability after store the epoxy compounding in 23° C and 40° C for 30 days. The temperature to measure the storage stability is 25° C $^{\circ}$

Result: the viscosity increase over the initial viscosity.

Report the increase rate in multiple times and / or days for viscosity of the epoxy compounding to increase up to 2 times high on the initial viscosity.

3. Property of the cured product.

Epoxy resin ⁽¹⁾ , Phr	100	100	100	100	100
Aerosil 300 ⁽²⁾	1	1	1	1	1
FXR-1081	10	15	20	25	30
Curing property measured by DSC. (3),°C					
Reaction start temp-1	67	67	67	66	67
Reaction start temp-2	95	93	91	90	89
Peak temperature.	116	114	113	111	110
Glass transition temp (4)	56	98	105	105	104
Bending strength (5), Mpa					
Curing at 70° C × 1h	_	28	90	91	87
80°C × 1h	111	118	125	126	126
100°C × 1h	111	113	115	117	120
120°C × 1h	100	105	105	104	110
Bending modulus (5), Gpa					
Curing at 70° C × 1h	_	1.0	2.9	3.4	3.5
80°C × 1h	3.3	3.3	3.5	3.6	3.5
100°C × 1h	3.0	2.8	2.7	2.6	2.7
120°C × 1h	2.7	2.3	2.3	2.4	2.4
Tensile strength (6), Mpa					
Curing at 70°C × 1h	_	11.5	14.0	14.8	14.9
80°C × 1h	16.5	16.0	15.9	15.0	15.0
100°C × 1h	19.8	18.9	17.5	15.5	15.5
120°C × 1h	23.5	21.7	20.5	18.3	19.0

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Boiling water absorption ⁽⁷⁾ , (wt%)					
Curing at 70° C × 1h	_	0.40	0.42	0.50	0.56
80°C × 1h	0.45	0.45	0.46	0.50	0.57
100°C × 1h	0.48	0.46	0.45	0.50	0.57
120°C × 1h	0.52	0.45	0.50	0.52	0.52

Remarks:

- (1) Bisphenol-A liquid epoxy resin whose epoxy equivalent weight is about 190.
- (2) Colloidal silica by Nippon Aerosil.
- (3) Measured from the curve of DSC.

Heating speed $=10^{\circ}$ C / min.

(4) Heating upto 220° C under heating speed 10° C/min.

Thereafter heat again under heating speed of 10°C/min.

Measured from DSC curve.

(5) Cure for one hour at each temperatoue.

Measure Bending strength and bending modulus.

(6) Apply the epoxy compounding onto mild steel sheet with sand blast.

Cure for one hour.

Measure the tensile strength under

The speed of 2mm/min.

(7) Encapsulate the compounding into a mold (diameter = 50mm. Height = 3mm).

Cure for one our.

Immerse the cured product in boiling water for one hour.

Thereafter, measured the weight increase of the cured product.

4. Accelerating property to D.I.C.Y

Epoxy resin (1), Phr	100	100	1,000	1,000	100
Aerosil 300 (2)	1	1	1	1	1
Amicure CG-1400 (3)	8	8	8	8	8
FXR-1081	_	1	3	5	7
Curing property measured by DSC. (4),°C					
Reaction start temp-1	159	122	72	68	70
Reaction start temp-2	188	162	128	117	111
Peak temperature.	198	176	149	140	135
Glass transition temp (5)	131	130	131	130	127
Gel time (6), (sec)					
at 100°C	_	_	2.289	1,039	651
at 120°C	_	_	557	289	214
at 150°C	_	450	142	117	96
at 180°C	293	139	89	71	64



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NO. 1, ZHONGSHAN S. RD., LUZHU DIST., KAOHSIUNG CITY, TAIWAN. TEL: 886-7-6962211~3 http://www.sanho.com.tw FAX: 886-7-6976993 (Sales) E-mail: sanho@sanho.com.tw FAX: 886-7-6961782 (Export) E-mail: sanho@so-net.net.tw

a. (7) #t ***					
Storage stability (7) 黏 Viscosity increase					
ratio (in multiple)	21.7	23.1	24.9	26.6	28.4
Initial Viscosity, Pa⋅S / 25°C	1.2	1.4	1.6	1.8	2.0
40° C × 30 days	1.1	1.1	1.1	1.1	1.1
23°C × 30days					
Gel time $^{(6)}$ $(40^{\circ}\text{C} \times 30\text{days})$ (sec)					
at 100°C	_	_	1,690	787	506
at 120°C	_	_	507	257	193
at 150°C	_	400	139	115	101
at 180°C	255	136	90	70	60
Gel time $^{(6)}$ (23°C × 30days)(sec)					
at 100°C	_	_	2,009	948	611
at 120°C	_	_	555	233	186
at 150°C	_	400	138	108	100
at 180°C	271	126	90	68	68
Tensile strength (7), Mpa					
Curing at 100℃×1 小時	_	_	_	11.5	19.7
120℃×1小時	_	_	23.1	22.0	20.6
150℃×1小時	_	27.0	25.9	24.2	24.5
180℃×1 小時	28.3	28.0	28.5	28.5	27.2

Remarks:

- (1) Bisphenol-A liquid epoxy resin whose epoxy equivalent weight is about 190.
- (2) Colloidal silica by Nippon Aerosil.
- (3) D. I.C.Y. by Air Products
- (4) Measured from the curve of DSC.

Heating speed = 10° C/min.

(5) Heating upto 220°C under heating speed 10°C / min.

(when using only CG-1400, upto 250° C)

Thereafter, heat again under heating speed of 10°C/min.

Measured from DSC curve.

- (6) Mass=2g, Measured by Yasuda model gel-timer.
- (7) Measure the storage stability after store the epoxy compounding in 23°C and 40°C for 30 days.

The temperature to measure the storage stability is 25° C.

Result: the viscosity increase over the initial viscosity.

Report the increase rate in multiple times and / or days for viscosity of the epoxy compounding to increase upto 2 times high on the initial viscosity.

(8) Apply the epoxy compounding onto mild steel sheet with sand blast.

Cure for one hour.

Measure the tensile strength under the speed of 2mm/min.